



## **TSD305**

# DIGITAL TEMPERATURE SENSORS

# **Product Description**

The TSD Series are digital thermopile sensors in a TO5 package. The TSD sensors include an infrared sensor (thermopile) and a sensor signal conditioner.

The TSD sensors can be interfaced to any microcontroller by an I<sup>2</sup>C interface. This microcontroller has to calculate the temperature results based on the ADC values and the calibration parameters

## **Features**

- 0°C ... up to +300°C measurement ranges
- Small size
- Small field of view available
- Up to ±1°C accuracy
- I<sup>2</sup>C Interface
- Low current consumption
- Operating Temperature Range: -10°C ... +85°C

# **Applications**

- Contactless temperature measurement
- Climate control
- Industrial process control
- Household applications

# **ABSOLUTE MAXIMUM RATINGS**

Absolute maximum ratings are limiting values of permitted operation and should never be exceeded under the worst possible conditions either initially or consequently. If exceeded by even the smallest amount, instantaneous catastrophic failure can occur. Even if the device continues to operate satisfactorily, its life may be considerably shortened.

Parameter	Symbol	Condition	Min	Тур	Max	Unit
Supply voltage	$V_{DD}$		-0.3		+3.63	V
Storage temperature	T <sub>stor</sub>	dry	-20		+85	°C
Voltage at supply and IO pins	V <sub>DD</sub> V <sub>IO</sub>		-0.5		V <sub>DD</sub> +0.5	V
Current into supply and IO pins	I <sub>IN</sub>		-100		100	mA
ESD rating	ESD	Human Body Model	-2		+2	kV
Humidity	Hum		No	on conden	sing	

## **OPERATING CONDITIONS**

If not otherwise noted, 3.3V supply voltage is applied.

Parameter	Symbol	Condition	Min	Тур	Max	Unit
Operating supply voltage	$V_{DD}$	stabilized, 100nF	1.68		3.6	V
VDD rise time	t <sub>VDD</sub>				200	μs
Operating temperature	T <sub>op</sub>		-20		+85	°C
Resolution	RES				0.1	°C
Supply Current		Active state, average		1050	1500	μΑ
Supply Current	I <sub>VDD</sub>	Sleep state, idle current		20	25	nA
Serial data clock I2C	F <sub>SCL</sub>		10	100	400	kHz
Self-heating	SH	1 sample/s, still air, 60s			+0.2	°C
VDD capacitor	C <sub>VDD</sub>	Place close to the sensor		100		nF

# THERMOPILE COMPONENT

If not otherwise noted, 3.3V supply voltage is applied.

Parameter	Symbol	Condition	Sensor	Min	Тур	Max	Unit
Absorber area	А			0.8 x 0.8		mm	
Field of view	FOV	At 50% of maximum signal	TSD305-1C55 TSD305-2C55 TSD305-3C55		88		deg
			TSD305-1SL10		10		deg
Filter transmission range		Long wave pass	TSD305-1C55 TSD305-2C55 TSD305-3C55	>5.5			μm
		Silicon lens, no coating	TSD305-1SL10	≥1.1			μm

# ANALOGUE TO DIGITAL CONVERTER

Parameter	Symbol	Condition	Min	Тур	Max	Unit
Resolution	ADC <sub>RES</sub>			16		bit
Conversion time	t <sub>CONV</sub>			44.8	59.2	ms
Rise time	t <sub>63</sub>	Including rise time of sensor element			44.8	ms
Resolution internal temperature sensor	ITS <sub>RES</sub>			0.003		K/LSB

# **OBJECT TEMPERATURE RANGE**

Parameter	Symbol	Sensor	Min	Тур	Max	Unit
	т	TSD305-1C55 TSD305-3C55	0		+100	°C
Object temperature range <sup>1)</sup>	T <sub>OBJ</sub>	TSD305-2C55 TSD305-1SL10	0		+300	°C

<sup>1)</sup> Other temperatures on request

# **TOLERANCES**

If not otherwise noted, 3.3V supply voltage is applied.

 $T_{sen}$  = sensor temperature,  $T_{obj}$  = object temperature

Parameter	Symbol	Sensor Temperature	Sensor	Object Temperature	Max	Unit
Acquirect Standard Town 1)	A.C.C	+15°C < T <sub>sen</sub> < +35°C	TSD305-1C55 TSD305-3C55	+40°C < T <sub>obj</sub> < +80°C	±1	%FS
Accuracy Standard Temp 1)	ACCs	+13 C < 1 <sub>sen</sub> < +33 C	TSD305-2C55 TSD305-1SL10	+170°C < T <sub>obj</sub> < +190°	1 ±1	%F3
		Complete range	TSD305-1C55	+40°C < T <sub>obj</sub> < +80°C		
Accuracy Extended Temp. 1 2)	400	+15°C < T <sub>sen</sub> < +35°C	TSD305-3C55	Complete range	+2	%FS
Accuracy Extended Temp. 1	ACC <sub>E1</sub>	Complete range	TSD305-2C55	TSD305-2C55 TSD305-1SL10 +170°C < T <sub>obj</sub> < +190° Complete range		701-3
		+15°C < T <sub>sen</sub> < +35°C	TSD305-1SL10			
Accuracy Extended Temp. 2 <sup>2)</sup>	ACC <sub>E3</sub>	Complete range	TSD305-1C55 TSD305-2C55 TSD305-3C55 TSD305-1SL10	Complete range	±3	%FS

Other temperature ranges and accuracies are available on request.

# **POWER & RESET**

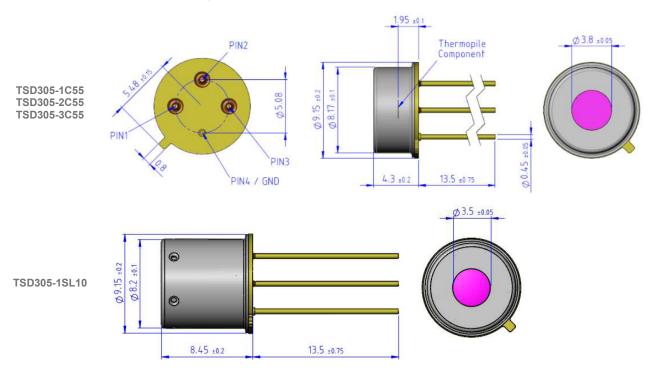
Parameter	Symbol	Condition	Min	Тур	Max	Unit
Start-up time	t <sub>STA1</sub>	V <sub>DD</sub> ramp up to interface communication			1	ms
	t <sub>STA2</sub>	V <sub>DD</sub> ramp to first ADC measurement			2.5	ms
Wake up time	t <sub>WUP1</sub>	Sleep to active state interface communication			0.5	ms
Trans up anno	t <sub>WUP2</sub>	Sleep to first ADC measurement			2	ms
Power down time for reset	t <sub>RESET</sub>	VDD <sub>low</sub>	3			μs
VDD low level	VDD <sub>low</sub>		0		0.2	V
VDD rising slope	SR <sub>VDD</sub>		10			V/ms

<sup>1)</sup> Ideal, proved by production

<sup>2)</sup> Ideal case by design

# **DIMENSIONS**

If not specified, all tolerances according DIN ISO 2768-m.



# PIN FUNCTION TABLE

Pin	Name	Туре	Function
1	SCL	DI	I <sup>2</sup> C Clock
2	SDA	DIO	I <sup>2</sup> C Data
3	$V_{DD}$	Р	Supply Voltage
4	V <sub>SS</sub>	Р	Ground

# I<sup>2</sup>C INTERFACE

An I<sup>2</sup>C communication message starts with a start condition and it is ended by a stop condition.

Most commands consist of two bytes: the address byte and command byte.

# I<sup>2</sup>C ADRESS

The standard I<sup>2</sup>C address is

Sensor	I2C Address Hex	I2C Address Bin
TSD305-1C55 TSD305-2C55 TSD305-1SL10	0x00	0b000000X
TSD305-3C55	0x1E	0b0011110X

X = 0: I<sup>2</sup>C Write
 X = 1: I<sup>2</sup>C Read

# Digital Thermopile Sensor

# STATUS BYTE

Each return starts with a status byte followed by the requested data word.

Bit	7	6	5	4	3	2	1	0
Meaning			Busy			Memory Error		

• Busy: 1 = Sensor is busy. The requested data is not available yet.

• Memory Error: 1 = Memory integrity check failed. Memory was changed after factory calibration.

## **COMMANDS**

Note: Each return starts with a status byte followed by the requested data word. Please take care to wait a certain time after write command before read data.

Command	Return	Description
0x00 0x39	16 bit EEPROM data	Read data from EEPROM address (0x00 0x39) matching the command
0xAF	24 bit object temperature ADC, 24 bit sensor temperature ADC	Measure object temperature and sensor temperature ADC 16 times and calculates mean value. Store data in output buffer.

## Read EEPROM

Write Command:



## Read EEPROM Data:

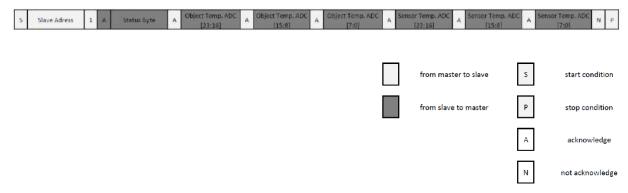


## Perform Measurement and Read ADC Data

Write Command:



## Read ADC Data:



# **EEPROM CONTENT**

Address / hex	Address / dec	Description	Name	Format	Exa	ımple
Address / Hex	Address / dec	Description	Name	Tomat	Content	Value
0x00	0	Lot Nr.		UINT16	15001	YY WWW
0x01	1	Serial Number		UINT16	12345	Number
0X02	2	I <sup>2</sup> C Address Valid range: 0x00 0x7F, 0x04 0x07 are reserved	I <sup>2</sup> CAdd	UINT16	0x00	0
0x03 0x19	2 25	Factory Calibration Data				
0x1A	26	Min. Sensor Temp. / °C	T <sub>SenMin</sub>	SINT16	0xFFEC	-20°C
0x1B	27	Max. Sensor Temp. / °C	T <sub>SenMax</sub>	SINT16	0x0055	+85°C
0x1C	28	Min. Object Temp. / °C	T <sub>ObiMin</sub>	SINT16	0x0000	0°C
0x1D	29	Max. Object Temp. / °C	$T_{ObjMax}$	SINT16	0x0064	100°C
0x1E	30	T		IEEE 754 H-Word	0xBB96	0.0040
0x1F	31	Temperature Coefficient	TC	IEEE 754 L-Word	0xBB99	-0.0046
0x20	32	D ( T )	_	IEEE 754 H-Word	0x41D7	00.00
0x21	33	Reference Temperature	T <sub>REF</sub>	IEEE 754 L-Word	0x70A4	26.93
0x22	34	Compensation	1.4	IEEE 754 H-Word	0x3A07	5 4045 0
0x23	35	Coefficient k4	k4 <sub>comp</sub>	IEEE 754 L-Word	0x4C8C	5.161E-04
0x24	36	Compensation		IEEE 754 H-Word	0x3F10	
0x25	37	Coefficient k3	k3 <sub>comp</sub>	IEEE 754 L-Word	0x5CEC	5.639E-0
0x26	38	Compensation		IEEE 754 H-Word	0x4367	
0x27	39	Coefficient k2	k2 <sub>comp</sub>	IEEE 754 L-Word	0x0D1F	2.311E+0
0x28	40	Compensation		IEEE 754 H-Word	0x4724	
0x29	41	Coefficient k1	k1 <sub>comp</sub>	IEEE 754 L-Word	0x5A6F	4.207E+0
0x2A	42	Compensation		IEEE 754 H-Word	0xC9A0	
0x2B	43	Coefficient k0	k0 <sub>comp</sub>	IEEE 754 L-Word	0x254D	-1.312E+0
0x2C	44					
0x2D	45	Not used				
0x2E	46	ADC → T		IEEE 754 H-Word	0x944B	
0x2F	47	Coefficient k4	k4 <sub>Obj</sub>	IEEE 754 L-Word	0xD24F	-1.029E-2
0x30	48	ADC → T		IEEE 754 H-Word	0x2052	
0x31	49	Coefficient k3	k3 <sub>Obj</sub>	IEEE 754 L-Word	0xF1C2	1.787E-1
0x32	50	ADC → T		IEEE 754 H-Word	0xABE5	
0x33	51	Coefficient k2	k2 <sub>Obj</sub>	IEEE 754 L-Word	0x991B	-1.631E-1
0x34	52	ADC → T		IEEE 754 H-Word	0x3797	
0x35	53	Coefficient k1	k1 <sub>Obj</sub>	IEEE 754 L-Word	0x2BBF	1.802E-0
0x36	54	ADC → T		IEEE 754 H-Word	0x41D7	
0x37	55	Coefficient k0	k0 <sub>Obj</sub>	IEEE 754 L-Word	0x41D7 0x6DBA	2.693E+0
0x38	56	Factory calibration status – internal usage only		UINT16	TBD	

# CHANGE OF I<sup>2</sup>C ADDRESS

The  $I^2C$  address of each TSD can be modified to use multiple TSDs on one  $I^2C$  bus. The used  $I^2C$  address is configured via an EEPROM address. Power needs to be cycled to active an updated  $I^2C$  address.

Command	Return	Description				
0x00 0x39	16 bit EEPROM data	Read data from EEPROM address (0x00 0x39) matching the command				
0x40 0x79		Write data from EEPROM address (0x00 0x39).				
0x90	****	Calculate and write memory checksum (CRC).  If the CRC is valid, then the "Memory Error" status bit is set to 0.				

The commands to read and write the EEPROM are shown below. After changing the I<sup>2</sup>C address, the checksum needs to be recalculated to reset the Memory Error bit.

## NUMBER FORMAT

## UINT16

Description: Unsigned integer

• Bits 16

Min (dec/hec/bin)
 Max (dec/hec/bin)
 Max (dec/hec/bin)
 Max (dec/hec/bin)
 Max (dec/hec/bin)

## SINT16

Description: Signed integer

• Bits 16

Min (dec/hec/bin) - 32,768 / 0x8000 / 0b1000 0000 0000 0000
 Max (dec/hec/bin) 32,767 / 0x7FFF / 0b0111 1111 1111 1111

## FLOAT IEEE 754

Description: FloatBits 32

Example: H-Word 0x3DCC L-Word 0xCCCD

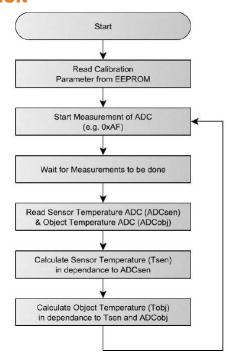
→ 0b0011 1101 1100 1100 1100 1100 1101

→ 0.1

## FLOAT IEEE 754 Conversions

The two integer words can easily be converted to a floating-point number by using a union consisting of an integer array and a float.

# **TEMPERATURE CALCULATION**



## SENSOR TEMPERATURE

The sensor temperature T<sub>Sen</sub> is calculated from the corresponding 24 bit ADC value ADC<sub>sen</sub>.

Name	Description	Format	Rai	nge
			Min Max	
ADC <sub>sen</sub>	ADC Sensor Temperature	INT24	0	16,777,216

ADCsen is scaled to cover the complete sensor temperature range from TsenMin to TsenMax.

Adress / hex	Adress / dec Description		Name	Format	Example	
						Max
0x1A	26	Min. Sensor Temp. / °C	$T_{SenMin}$	SINT16	0xFFEC	-20°C
0x1B	27	Max. Sensor Temp. / °C	T <sub>SenMax</sub>	SINT16	0x0055	+85°C

Formula:

$$T_{sen}$$
 = ADC<sub>sen</sub> /  $2^{24} \times (T_{SenMax} - T_{SenMin}) + T_{SenMin}$ 

Example:

$$ADC_{sen} = 6,364,157$$

$$T_{sen} = 6,364,157 / 224 \times [+85^{\circ}C - (-20^{\circ}C)] + (-20^{\circ}C) = \underline{19.83^{\circ}C}$$

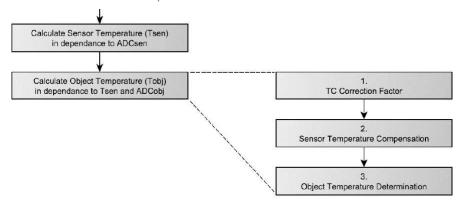
# **OBJECT TEMPERATURE**

The object temperature Tobj is calculated in dependence of the sensor temperature Tsen and ADCobj.

ADC<sub>obj</sub> is shifted by 2<sup>23</sup> in order to provide unsigned integer values for positive and negative measurement values.

Name	Description	Format	Range	
	·		Min	Max
ADC <sub>obj</sub>	ADC Object Temperature Shifted by 2 <sup>23</sup> (0 is represented by 8,388,608)	INT24	0	16,777,216

The process consists of three successive steps.



## TC Correction Factor

Adress / hex	Adress / dec	Description	Name	Format	Example	
, aroso, nox	71010007 000			T OTHER	Content	Value
0x1E	30	Towns and two Coofficient	TO	IEEE 754 H-Word	0xBB96	0.0040
0x1F	31	Temperature Coefficient	TC	IEEE 754 L-Word	0xBB99	-0.0046
0x20	32	Deference Temperature	e T <sub>REF</sub>	IEEE 754 H-Word	0x41D7	126.02
0x21	33	Reference Temperature		IEEE 754 L-Word	0x70A4	+26.93

= 1.0327

# Temperature Compensation

Adress / hex	Adress / dec	Description	Name	Format	Example	
					Content	Value
0x22	34	Compensation	le4	IEEE 754 H-Word	0x3A07	E 161E 04
0x23	35	Coefficient k4	k4 <sub>comp</sub>	IEEE 754 L-Word	0x4C8C	5.161E-04
0x24	36	Compensation	k2	IEEE 754 H-Word	0x3F10	5.639E-01
0x25	37	Coefficient k3	Coefficient k3	IEEE 754 L-Word	0x5CEC	5.039E-01
0x26	38	Compensation	k2	IEEE 754 H-Word	0x4367	2.311E+02
0x27	39	Coefficient k2	k2 <sub>comp</sub>	IEEE 754 L-Word	0x0D1F	2.311E+02
0x28	40	Compensation	k1	IEEE 754 H-Word	0x4724	4.207E+04
0x29	41	Coefficient k1	1 k1 <sub>comp</sub> -	IEEE 754 L-Word	0x5A6F	4.207 = +04
0x2A		Compensation	k0	IEEE 754 H-Word	0xC9A0	-1.312E+06
0x2B		Coefficient k0	k0 <sub>comp</sub>	IEEE 754 L-Word	0x254D	-1.31ZETU0

Formula:		Example:	
		T <sub>sen</sub> =	+19.83°C
		k4comp k0comp	See table above
Offset =	$k4_{comp} \times Tsen^4$ + $k3_{comp} \times Tsen^3$ + $k2_{comp} \times Tsen^2$ + $k1_{comp} \times Tsen$ + $k0_{comp}$	Offset =	$= 5.161 \cdot 10^{-4} \times 19.83^{4}$ $+ 5.639 \cdot 10^{-1} \times 19.83^{3}$ $+ 2.311 \cdot 10^{2} \times 19.83^{2}$ $+ 4.207 \cdot 10^{4} \times 19.83$ $+ -1.312 \cdot 10^{6}$
			= -382,399
Offset <sub>TC</sub> =	Offset × TCF	Offset <sub>TC</sub> =	= -382,399 × 1.0327
			= -394,904

# **Object Temperature Determination**

Adress / hex	Adress / dec	Description	Name	Name Format		Example	
					Content	Value	
0x2E	46	ADC → T	1,4	IEEE 754 H-Word	0x944B	1 0205 26	
0x2F	47	Coefficient k4	k4 <sub>Obj</sub> -	IEEE 754 L-Word	0xD24F	-1.029E-26	
0x30	48	ADC → T	1,2	IEEE 754 H-Word	0x2052	1.787E-19	
0x31	49	Coefficient k3	k3 <sub>Obj</sub>	IEEE 754 L-Word	0xF1C2	1.707E-19	
0x32	50	ADC → T	14.0	IEEE 754 H-Word	0xABE5	-1.631E-12	
0x33	51	Coefficient k2	k2 <sub>Obj</sub>	IEEE 754 L-Word	0x991B	1 -1.031E-12	
0x34	52	ADC → T	lz 1	IEEE 754 H-Word	0x3797	1.802E-05	
0x35	53	Coefficient k1	ient k1	IEEE 754 L-Word	0x2BBF	1.002E-05	
0x36	54	ADC → T	kO	IEEE 754 H-Word	0x41D7	2.693E+01	
0x37	55	Coefficient k0	k0 <sub>Obj</sub>	IEEE 754 L-Word	0x6DBA	2.093E+01	

Formula:		Example:	
		ADC <sub>Obj</sub> =	10,738,758
		k4 <sub>Obj</sub> k0 <sub>Obj</sub>	See table above
ADC <sub>Comp</sub> =	Offset <sub>TC</sub> + $(ADC_{Obj} - 2^{23})^1$	ADC <sub>comp</sub> =	= -394,904 + 10,738,758 - 8,388,608 = 1,955,246
ADCcompTC =	ADC <sub>Comp</sub> / TCF	ADC <sub>CompTC</sub> =	= 1,955,246 / 1.0327 = 1,893,334
T <sub>Obj</sub> =	$\begin{array}{l} k4_{Obj} \times ADC_{CompTC}^4 \\ + k3_{Obj} \times ADC_{CompTC}^3 \\ + k2_{Obj} \times ADC_{CompTC}^2 \\ + k1_{Obj} \times ADC_{CompTC} \\ + k0_{Obj} \end{array}$	Тоы =	= $-1.029 \cdot 10^{-26} \times 1,893,334^4$ + $1.787 \cdot 10^{-19} \times 1,893,334^3$ + $-1.631 \cdot 10^{-12} \times 1,893,334^2$ + $1.802 \cdot 10^{-5} \times 1,893,334$ + $2.693 \cdot 10$
			= <u>56.28°C</u>

 $<sup>^1</sup>$  Valid if emissivity is 1 (100%). Otherwise the formula in brackets must be replaced by (ADCobj -  $2^{23})$  /  $\epsilon$ . See chapter "Emissivity" on page 13 for details.

## **Example Code**

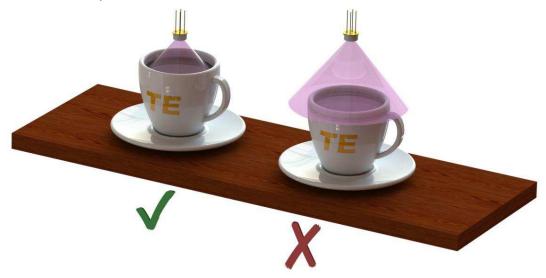
This example code is meant to illustrate the basic procedure to determinate the measured sensor and object temperatures with respect to TSD digital thermopile sensors. This code needs to be modified with respect to the compiler used.

```
// File: TSD Temperature_Determination_Example.c //
// Date: 01.\overline{1}1.2016 //
// Description: This example code is meant to illustrate the basical procedure //
// to determinat the measured sensor and object temperatures with //
// respect to TSD digital thermopile sensors. //
// This code is not meant to work or to be compiled. //
void TSD Determinate Temperature(void)
       signed int siMinObjTemp, siMaxObjTemp, siMinSenTemp, siMaxSenTemp;
       float fTC, fTref, fK4com, fK3com, fK2com, fK1com, fK0com, fK4obj, fK3obj,
       fK2obj, fK1obj, fK0obj;
       float fTsen, fTobj;
float fTCF, fOffset, fADCcomp;
       signed long slADC Object, slADC Sensor;
       // Read Temperature Range Minimum & Maximum
       siMinSenTemp = (signed int)Read EE UInt(26);
       siMaxSenTemp = (signed int)Read EE UInt(27);
       siMinObjTemp = (signed int)Read_EE_UInt(28);
       siMaxObjTemp = (signed int)Read EE UInt(29);
       // Read all necessary coefficients from the memory, float tye
       fTref = Read EE Float (32);
       fTC = Read EE Float(30);
       fTref = Read EE Float (32);
       fK4com = Read EE Float(34);
       fK3com = Read EE Float (36);
       fK2com = Read_EE_Float(38);
       fK1com = Read EE Float(40);
       fK0com = Read EE Float(42);
       fK4obj = Read EE Float (46);
       fK3obj = Read_EE_Float(48);
       fK2obj = Read EE Float(50);
       fK1obj = Read EE Float (52);
       fK0obj = Read EE Float (54);
       // Read ADC Values for Object Temp. & Sensor Temp.
       Read ADC Values (&slADC Object, &slADC Sensor);
       // Calculate Sensor Temp. (slADC_Sensor, Minimum & Maximum Sensor Temp.), Page 8
       fTsen = (float)slADC Sensor / 16777216.0 * (siMaxSenTemp - siMinSenTemp) + siMinSenTemp;
       // Calculate TC Correction Factor (Temp. Coefficient & Reference Temp.), Page 9fTCF = 1.0
       + ((fTsen - fTref) * fTC);
       // Calculate Offset Value, Page 10
       fOffset = fOffset + fK4com * fTsen * fTsen * fTsen * fTsen;
       fOffset = fOffset + fK3com * fTsen * fTsen * fTsen;
       fOffset = fOffset + fK2com * fTsen * fTsen;
       fOffset = fOffset + fK1com * fTsen;
       fOffset = fOffset + fK0com;
       fOffset = fOffset * fTCF;
       // Align ADC Value for Object Temperature, Page 11
       slADC Object = slADC Object - 8388608;
       // Calculate Object Temperature, Page 11
       fADCcomp = (float)slADC_Object + fOffset;
       fADCcomp = fADCcomp / fTCF;
       fTobj = fTobj + fK4obj * fADCcomp * fADCcomp * fADCcomp;
       fTobj = fTobj + fK3obj * fADCcomp * fADCcomp * fADCcomp;
       fTobj = fTobj + fK2obj * fADCcomp * fADCcomp;
       fTobj = fTobj + fKlobj * fADCcomp;
       fTobj = fTobj + fKOobj;
       // Resulting Sensor Temperature = fTsen
       // Resulting Object Temperature = fTobj
 1
```

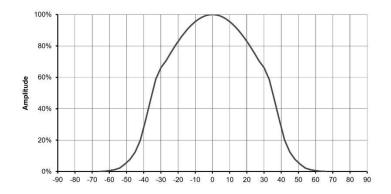
# **APPLICATION NOTES**

# FIELD OF VIEW

The thermopile's field of view must be directed to the object surface of interest. The distance to the surface or the surface diameter must be adjusted to ensure that the complete sensors field of view is covered by the object, see example on the left in the picture below.

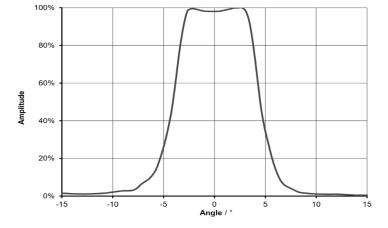


TSD305-1C55 TSD305-2C55



Distance / mm	Min. Diameter / mm
10	24
20	43
30	62
40	82
50	101
100	198
200	391
300	584
400	777
500	970





Distance / mm	Min. Diameter / mm
10	6
20	8
30	10
40	11
50	13
100	22
200	39
300	57
400	74
500	92

# **DIRECT SUNLIGHT**

Sun light radiation which is transmitted through a glass window may influence the measurement accuracy. To avoid this, the thermopile sensor is equipped with a long wavelength filter. Due to not ideal filter characteristics a small portion of radiation will be added to the radiation of the object. In case of direct sunlight exposure this error can be up to  $+0.2^{\circ}$ C.

## TOUCHING THE SENSORS CAP

User should avoid touching the sensors cap. There will still be a measurement deviation after changing the sensors temperature rapidly.

## **EMISSIVITY**

Every object is transmitting infrared energy in dependence to its temperature. The emissivity is the ratio of the radiated power by an object to the radiation of an ideal black body. Common materials like liquids, clothes, human skin, foods have emissivity factors >0.90 and therefore they can be measured very accurately without adopting the sensors specification.

To compensate the measurement for an object with significant low emissivity, ADCobj needs to be adjusted.

Name	Description	Format	Range	
	23337,1333		Min	Max
ADC <sub>obj</sub>	ADC Object Temperature Shifted by 2 <sup>23</sup> (0 is represented by 8,388,608)	INT24	0	16,777,216
ε	Emissivity	100%	0	1

Formula: Example:

ADC<sub>Obj</sub> = 10,738,758 $\epsilon = 0.9 (90\%)$ 

ADC<sub>Corr</sub> =  $(ADC_{Obj} - 2^{23}) / \varepsilon$  ADC<sub>Corr</sub> = = 2,611,278

Material	Emissivity	
Aluminum		
Polished	0.10 - 0.05	
Oxidized	0.10 - 0.40	
Rough	0.10 - 0.30	
Anodized	0.60 - 0.95	
Asphalt	0.90 - 1.00	
Brass		
Polished	0.05	
Oxidized	0.50 - 0.60	
Burnished	0.30	
Ceramic	0.90 - 0.95	
	^	

Asphalt	0.90 – 1.00			
Brass				
Polished	0.05			
Oxidized	0.50 - 0.60			
Burnished	0.30			
Ceramic	0.90 - 0.95			
Copper				
Polished	0.10			
Oxidized	0.20 - 0.80			
Foods	0.85 - 1.00			
Gold	0.05			
Glass				
Plate	0.90 - 0.95			
Fused quartz	0.75			

Material	Emissivity			
Human Skin	0.99			
Iron				
Polished	0.20			
Oxidized	0.50 - 0.95			
Rusted	0.50 - 0.70			
Paint				
Aluminum paint	0.50			
Bronze paint	0.80			
On metal	0.60 - 0.90			
On plastic, wood	0.80 - 0.95			
Paper	0.85 - 1.00			
Plastic	0.95 - 1.00			
Stainless Steel				
Polished	0.10 - 0.15			
Oxidized	0.45 - 0.95			
Water				
Liquid	0.90 - 0.95			
Ice	0.95 - 1.00			
Snow	0.80 - 1.00			

## **EVALUATION KIT**

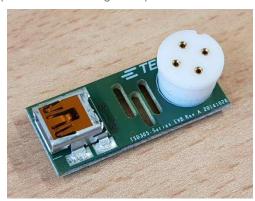
## **GENERAL DESCRIPTION**

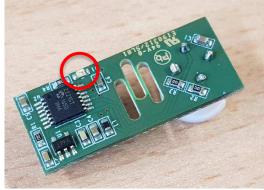
For easy usage and first trials an evaluation kit is available. It consists of an evaluation board and the "DTS-Viewer"-Software. The eval-board provides an USB to I<sup>2</sup>C interface and can be used on Windows PCs and Android Smartphones with an OTG capable USB port. That means that for example USB flash drives can be connected by an OTG cable to the phone.

The "DTS-Viewer"-Software enables easy measurements and datalogging. This software is available for Windows and Android and supports a wide range of digital temperature sensors provided by TE.

## **EVALUATION BOARD HARDWARE DESCRIPTION**

The following pictures are showing the top and the bottom side of the eval board PCBA.





It is equipped with the Microchip™ MPC2221 USB to I²C transceiver, a voltage regulator and some passive components. A status LED (red circle) on the bottom of the PCBA indicates power supply and data transmission.

The TSD must be plugged into the white TO socket; the indicator flag of the TSD has to be matched with notch at the socket. The connection to the PC has to be done by a USB cable with Mini-USB-B-plug on the module's side. For connecting to a smartphone an OTG cable is required. This type of cable is used to connect a slave USB device to the USB connector of the smartphone.

## **LED Function Table**

On state	Function	
On	Power on	
Flashing	Access / data transmission	

## DTS-VIEWER DESCRIPTION (PC VERSION)

## Overview

The software read out suitable temperature sensors that communicate with an MCP2221 via USB.

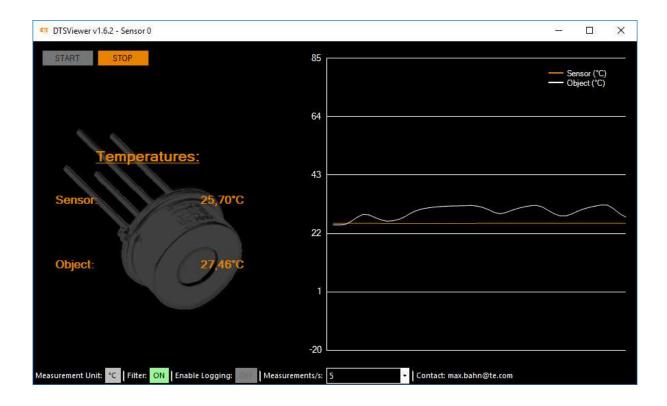
The software can display the temperatures measured by the respective sensor and at the same time display the time course of the last 50 measured values in a graph.

In addition, the measured temperatures can be recorded in a text file via the logging function.

During the measurement it is possible to put a filter over the measured values and to vary the measuring speed in given intervals.

To use the software no special installation process is required. Just start the executable file on the USB flash drive that is provided with the evaluation kit.

The following picture shows the main window that appears after starting the executable file.



## Measurement

First, the evaluation board equipped with a TSD must be connected to the PC.

By pressing the START-button the measurement of both temperatures, sensor package and object temperature is started.

Pressing the STOP-button stops the measurement. Disconnecting the sensor board from the PC has the same effect.

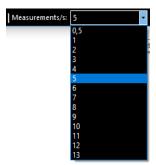
## Switching the temperature Unit

The temperature unit can be changed only when the measurement is running. This is done by clicking on the "Measurement Unit"-Symbol on the lower left area. °C and °F can be selected.

## Measurement Speed

In the drop-down menu "Measurements/s" the measurement speed can be selected, both before and during a running measurement.

You can select from a predefined selection of measurement speeds. The minimum measurement interval is limited by the internal measurement speed of the sensor.



Digital Thermopile Sensor

#### Filter

The "Filter" button enables or disables a filter to smooth the measured values. It can be pressed before or during measurement.

The filter used is a very simple implementation of a moving average filter, which is only intended to provide smoothing for unstable measured values. In this implementation the filter considers the last 5 measured values.

Note: If the measured values must be as accurate as possible or if a fast reaction time is required, the filter should be switched off.

# Logging

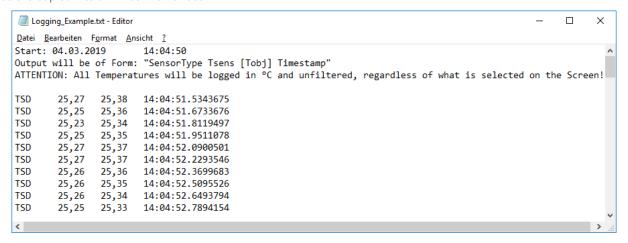
The software can record the measurement data in a text file. The "Enable Logging" button toggles between recording on and

If the logging is set to "ON" the user is prompted to select or create a text file which is then used to save the measurement data each time he starts the measurement.

The text file begins with the time and date information and a description of the format used. Then follows the listing of the measured values, together with sensor type and an individual time stamp.

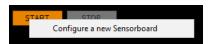
It should be noted that the measured values are always stored in °C and unfiltered, regardless of what the user has previously set in the program. Only the measuring speed has an influence on the stored data.

Note: The measurement data are stored as tabulator delimited values, so each value is written into a new cell if the measured values are copied into an Excel worksheet.



## Configuring a new Sensorboard – internal usage only

To use this function, the user must right-click on the "START" button and then click on the button that appears.



This function is for internal usage only and could lead to malfunction of the evaluation board. If the user activates the function by accident he should leave everything as it is and skip it.

## **ORDER INFORMATION**

Further customer specific adaptations are available on request. Please refer to the table below for part name, description and order information.

Part Number	Part Desription	Comment
G-TPMO-101	TSD305-1C55 Digital Thermopile Sensor	TO5, I <sup>2</sup> C Interface, 0°C +100°C
G-TPMO-102	TSD305-2C55 Digital Thermopile Sensor	TO5, I <sup>2</sup> C Interface, 0°C +300°C
G-TPMO-103	TSD305-3C55 Digital Thermopile Sensor	TO5, I <sup>2</sup> C Interface Add=0x1E, 0°C +100°C
G-TPMO-104	TSD305-1SL10 Digital Thermopile Sensor	TO5, FOV=10°, I <sup>2</sup> C Interface, 0°C +300°C
20006766-00	TSD305-Series Evaluation Kit	Contents evaluation board, one piece G-TPMO-101 and 104 and the DTS-Viewer software on USB drive

## **EMC**

Due to the use of these modules for OEM application no CE declaration is done. Especially line coupled disturbances like surge, burst, HF etc. cannot be removed by the module due to the small board area and low-price feature. There is no protection circuit against reverse polarity or over voltage implemented. The module will be designed using capacitors for blocking and ground plane areas in order to prevent wireless coupled disturbances as good as possible.

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